



STP2301 Pb
Lead-free
P Channel Enhancement Mode MOSFET

-2.8A

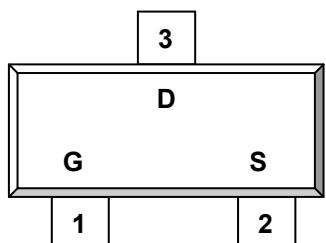
DESCRIPTION

The STP2301 is the P-Channel logic enhancement mode power field effect transistor is produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other batter powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

PIN CONFIGURATION SOT-23

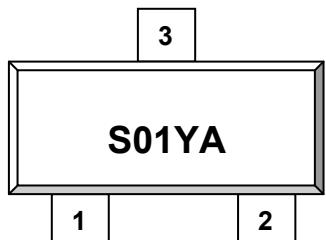


1.Gate 2.Source 3.Drain

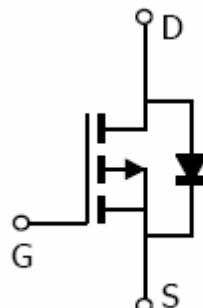
FEATURE

- -20V/-2.8A, $R_{DS(ON)} = 90\text{m-ohm}$ (Typ.)
@ $V_{GS} = -4.5\text{V}$
- -20V/-2.0A, $R_{DS(ON)} = 110\text{m-ohm}$
@ $V_{GS} = -2.5\text{V}$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

PART MARKING SOT-23



Y: Year Code A: Process Code





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ABSOLUTLE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V _{DSS}	-20	V
Gate-Source Voltage		V _{GSS}	±12	V
Continuous Drain Current TJ=150°C)	T _A =25°C T _A =70°C	I _D	-2.8 -1.5	A
Pulsed Drain Current		I _{DM}	-10	A
Continuous Source Current (Diode Conduction)		I _S	-1.6	A
Power Dissipation	T _A =25°C T _A =70°C	P _D	1.25 0.8	W
Operation Junction Temperature		T _J	150	°C
Storage Temperature Range		T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient		R _{θJA}	120	°C/W



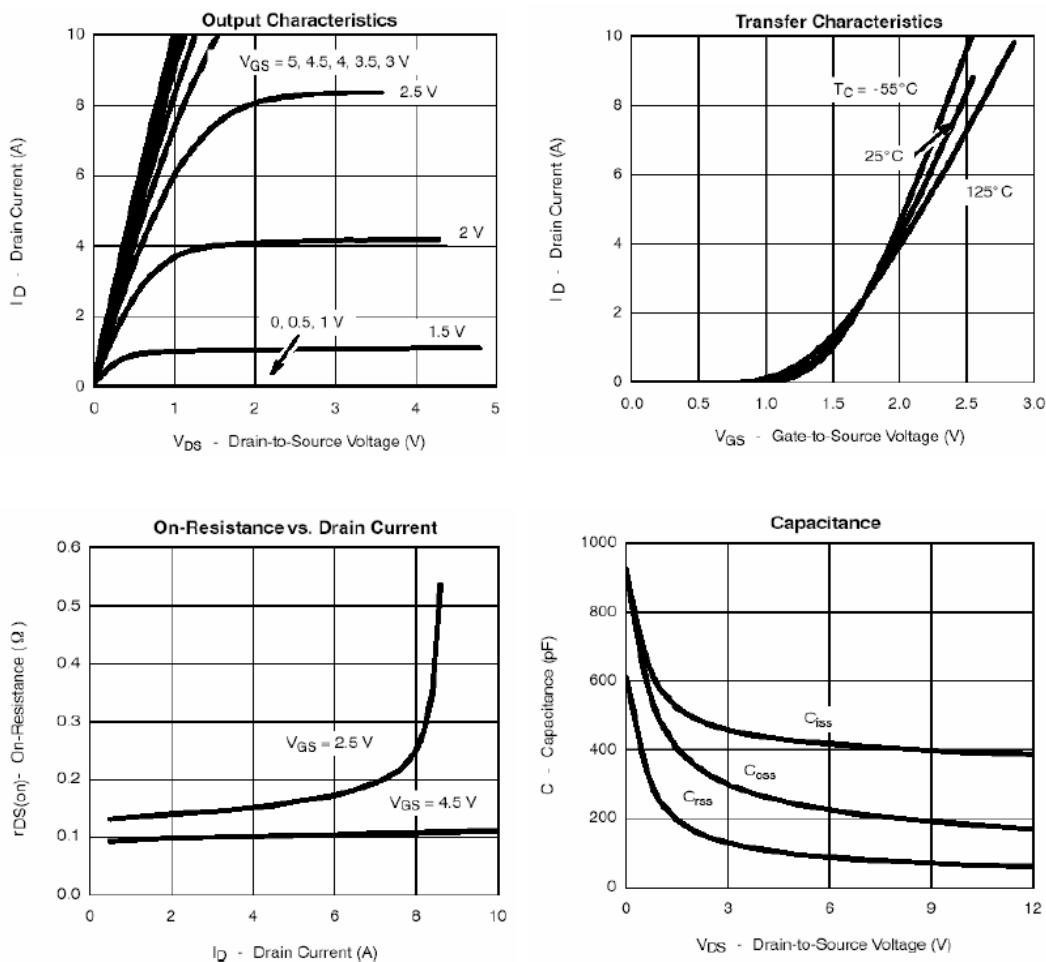
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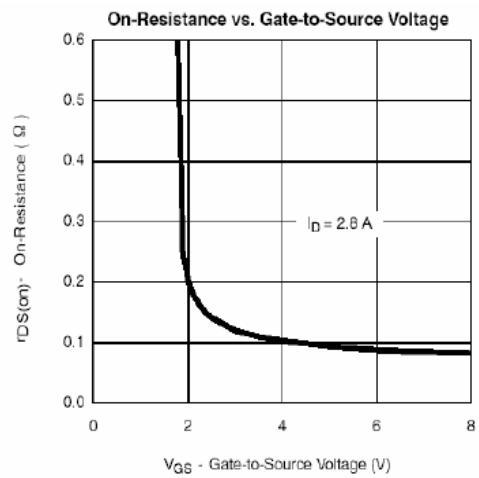
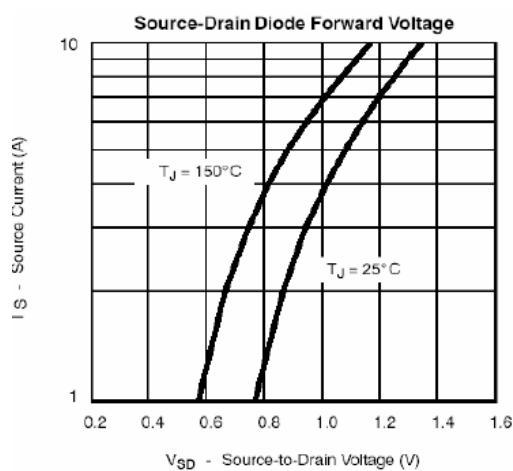
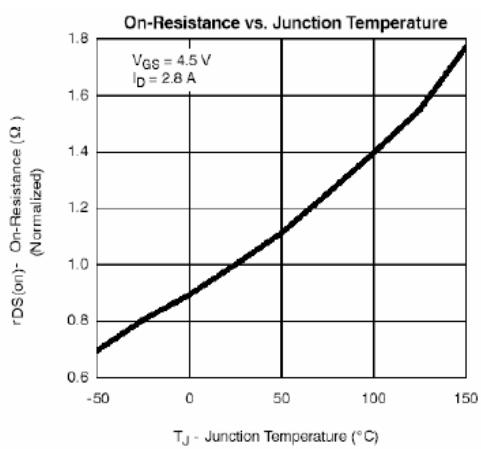
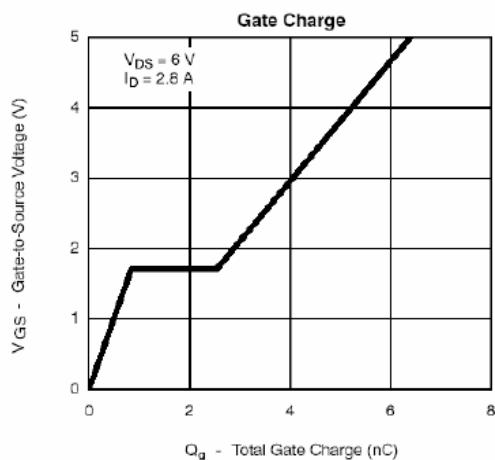
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ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	-20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	-0.4		-1.0	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V			-1	uA
		V _{DS} =-20V, V _{GS} =0V T _J =55°C			-10	
Drain-source On-Resistance	R _{D5(on)}	V _{GS} =-4.5V, I _D =-2.8A V _{GS} =-2.5V, I _D =-2.0A	0.090 0.110			Ω
Forward Transconductance	g _{f5}	V _{DS} =-5V, I _D =-2.8V		6.5		S
Diode Forward Voltage	V _{SD}	I _S =-1.6A, V _{GS} =0V		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-6V V _{GS} =-4.5V I _D =-2.8A		4.8	8	nC
Gate-Source Charge	Q _{gs}			0.75		
Gate-Drain Charge	Q _{gd}			1.4		
Input Capacitance	C _{iss}	V _{DS} =-6V V _{GS} =0V F=1MHz		35		pF
Output Capacitance	C _{oss}			150		
Reverse Transfer Capacitance	C _{rss}			60		
Turn-On Time	t _{d(on)} tr	V _{DD} =-6V R _L =6Ω I _D =-1A V _{GEN} =-4.5V R _G =6Ω		10	20	nS
Turn-Off Time	t _{d(off)} tf			32	45	
				38	55	
				30	50	

TYPICAL CHARACTERISTICS (25°C Unless noted)


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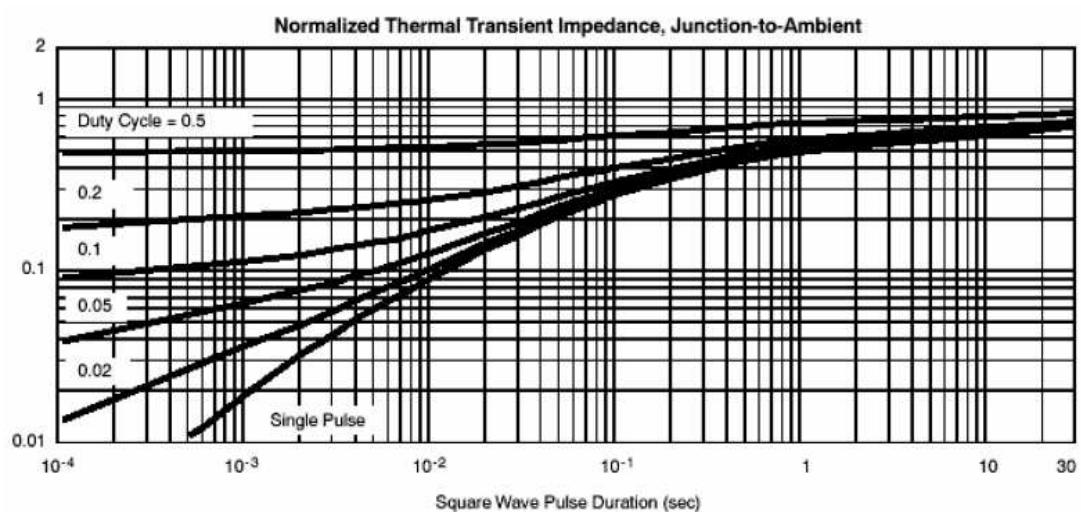
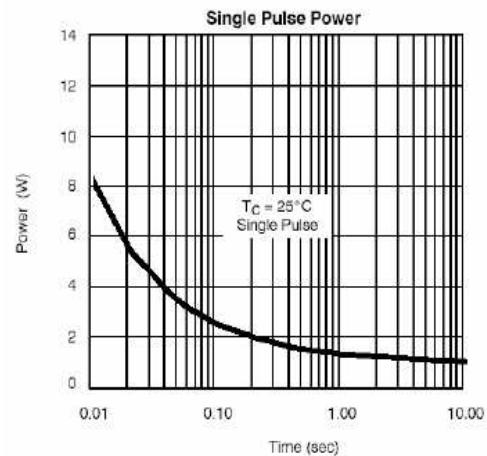
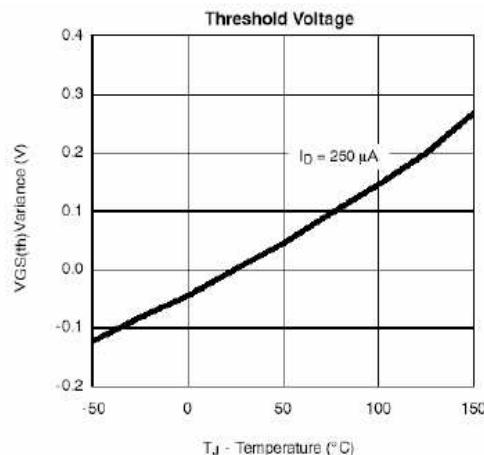


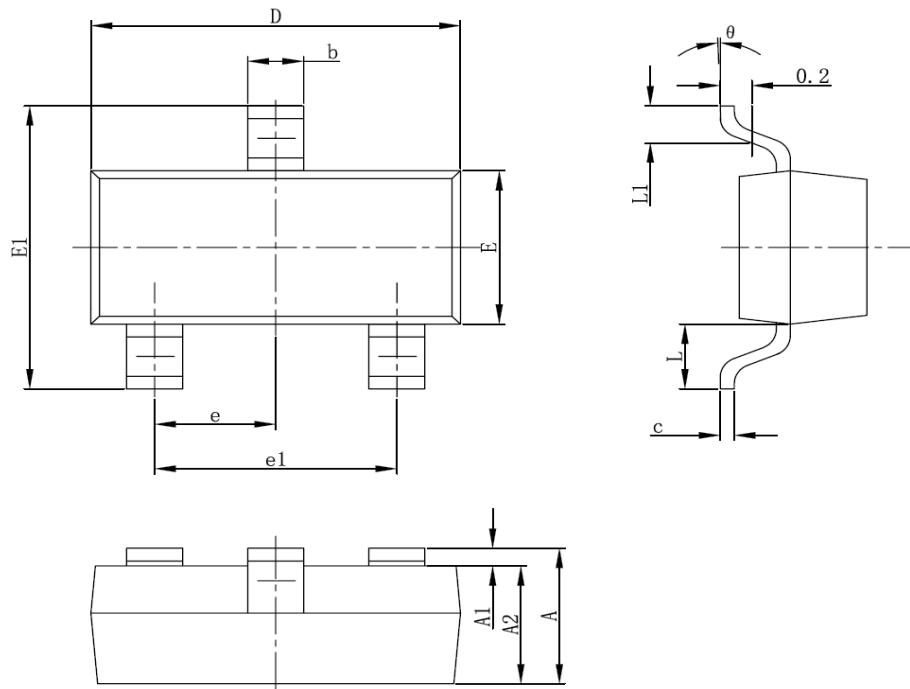
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SOT-23 PACKAGE OUTLINE


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°